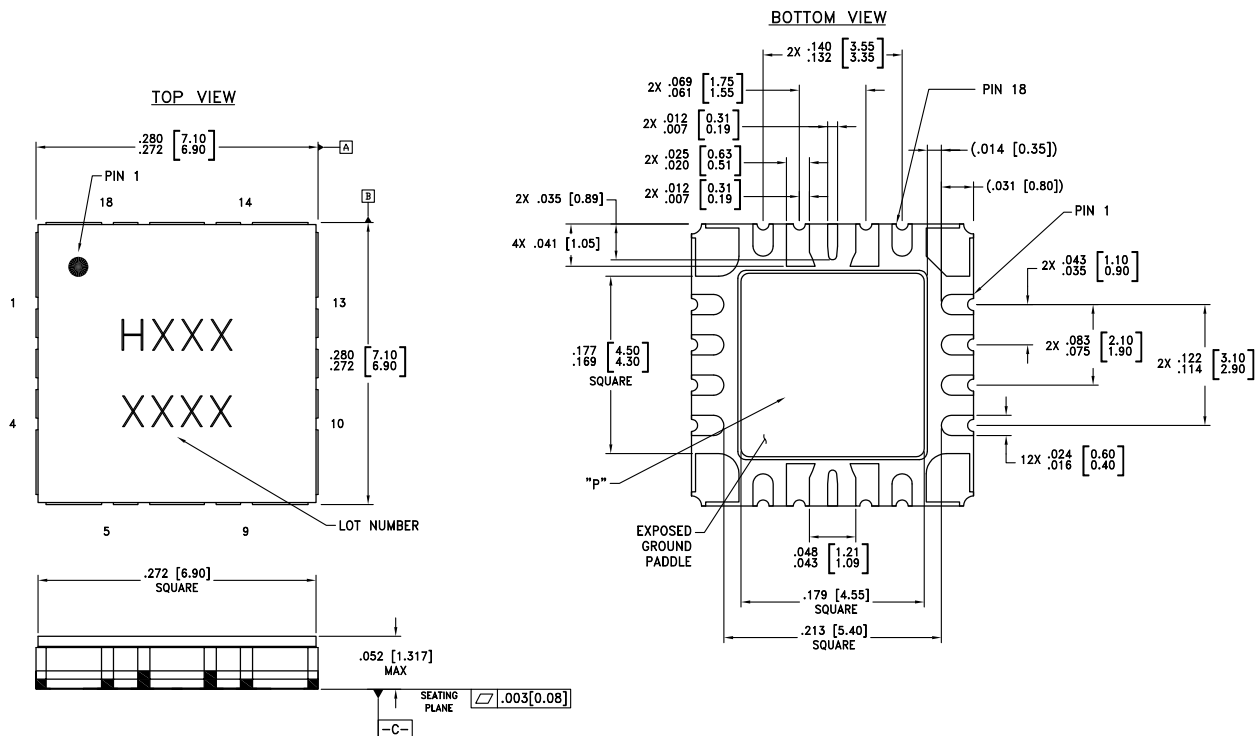


LS7 – 7 x 7 mm LEADLESS CERAMIC PACKAGE

LS7 Package Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA, WHITE
2. LEAD AND GROUND PADDLE PLATING: ELECTROLESS Ni PLATE 118uin (3.0um) NOM AND ELECTROLESS Au 25–50uin (0.635–1.27um). PLATING THICKNESS MEASURED ON POINT "P".
3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE, DIMENSIONS LOCATED ABOUT $\overline{-A-}$ AND $\overline{-B-}$ WITHIN .005".
5. CHARACTER TO BE INK OR LASER MARKED WITH .018" MIN TO .030" MAX HEIGHT REQUIREMENTS. UTILIZE MAXIMUM CHARACTER HEIGHT BASED ON LID DIMENSIONS AND BEST FIT. LOCATE APPROX. AS SHOWN.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating ^[2]	Package Marking ^[1]
HMCXXXLS7	ALUMINA WHITE	Gold over Nickel	MSL3	HXXX XXXX

[1] 4-Digit lot number XXXX.

[2] Max peak reflow temperature of 260 °C.

**LS7 – 7 x 7 mm
LEADLESS CERAMIC PACKAGE**

Suggested LS7 PCB Land Pattern

